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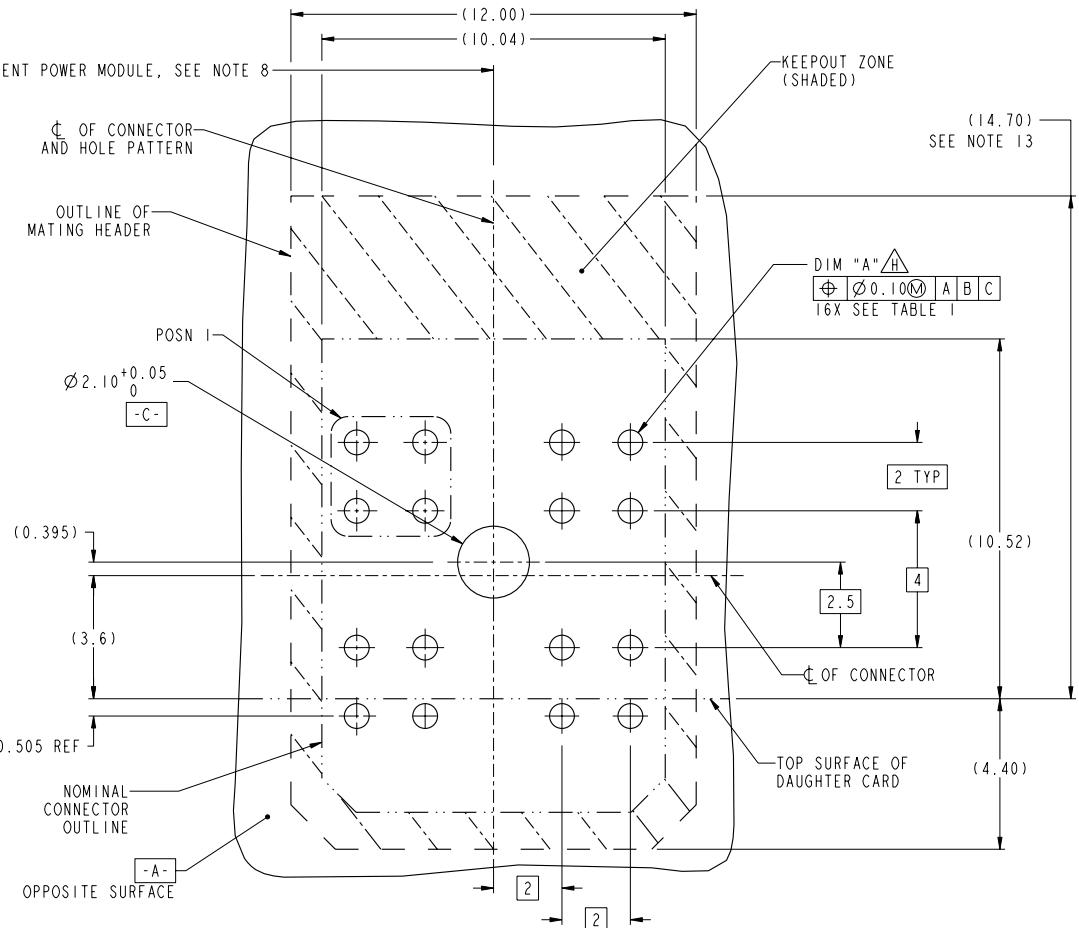
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PDM: Rev:H

STATUS: **Released**

Printed: Jul 03, 2010

I	2	3	4	5	6	7	8		
A	TOP LAYER DESCRIPTION	TABLE I PLATED THROUGH-HOLE REQUIREMENTS							
		DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	NICKEL THICKNESS	GOLD THICKNESS	TIN THICKNESS	SILVER THICKNESS	FINISHED HOLE DIAMETER (DIM "A") <sup>△</sup>
	TIN-LEAD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	0.005 - 0.015	--	--	--	--	0.65 - 0.80
	IMMERSION TIN	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	0.9 - 1.5 $\mu$ m	--	0.70 - 0.80
	IMMERSION SILVER	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	--	0.15 - 0.65 $\mu$ m	0.70 - 0.80
	COPPER (SEE NOTE 12)	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	--	--	0.70 - 0.80
	GOLD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	0.003 - 0.007	FLASH UP TO 0.0002	--	--	0.69 - 0.80
B	NOTES:								
1.	CONNECTOR MATERIALS: HOUSING: HIGH TEMPERATURE THERMOPLASTIC, BLACK UL 94V-0 COMPLIANT CONTACT: HIGH PERFORMANCE COPPER ALLOY								
2.	CONTACT PLATING: PRESS-FIT TAIL: 0.5 $\mu$ m TIN-LEAD OVER NICKEL. SEPARABLE INTERFACE: 0.76 $\mu$ m MIN GOLD OVER NICKEL.								
3.	CONTACT PLATING (LEAD-FREE): PRESS-FIT TAIL: 0.5 $\mu$ m MIN MATTE TIN OVER NICKEL. SEPARABLE INTERFACE: 0.76 $\mu$ m MIN GOLD OVER NICKEL.								
4.	PRODUCT SPECIFICATION: GS-12-220								
5.	APPLICATION SPECIFICATION: GS-20-023								
6.	PRODUCT MARKING (PRODUCT NUMBER & LOT CODE) ON HOUSING IN AREA SHOWN, EITHER SIDE.								
7.	MINIMUM NOMINAL BOARD THICKNESS: 2.4mm								
8.	REFER TO CUSTOMER DRAWING SK10035911 FOR INFORMATION REGARDING PCB LAYOUT OF POWER AND GUIDE MODULES RELATIVE TO AIRMAX SIGNAL MODULES.								
9.	PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN FCI SPECIFICATION GS-22-008.								
10.	PACKAGING MEETS FCI SPECIFICATION GS-14-920								
11.	HOUSING COMPONENT WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 60 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR-PHASE REFLOW OVEN.								
12.	COPPER PLATING THICKNESS AT CENTER OF VIA HOLE CAN BE NO MORE THAN 0.003 LESS THAN OTHER AREAS.								
13.	KEEPOUT AREA APPLICABLE FOR HIGH PROFILE POWER HEADER WITH 14.70MM HEIGHT ABOVE TOP SURFACE OF DAUGHTER CARD. IT MAY BE 11.5MM IF A LOWER PROFILE HEADER IS USED.								
14.	A <sup>△</sup> SYMBOL WILL BE NEXT TO ANY DIMENSION, VIEW, OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION								
C	RECOMMENDED PCB LAYOUT, COMPONENT SIDE SEE NOTE 7 SCALE 10:1							F	
D	RECOMMENDED PCB LAYOUT, COMPONENT SIDE SEE NOTE 7 SCALE 10:1							D	
E	RECOMMENDED PCB LAYOUT, COMPONENT SIDE SEE NOTE 7 SCALE 10:1							E	
F	RECOMMENDED PCB LAYOUT, COMPONENT SIDE SEE NOTE 7 SCALE 10:1							F	
I								8	



<b>FCI</b>	RECEPTACLE ASSEMBLY, POWER	catalog no	10028916	Rev. H
			CUSTOMER	sheet 2 of 2